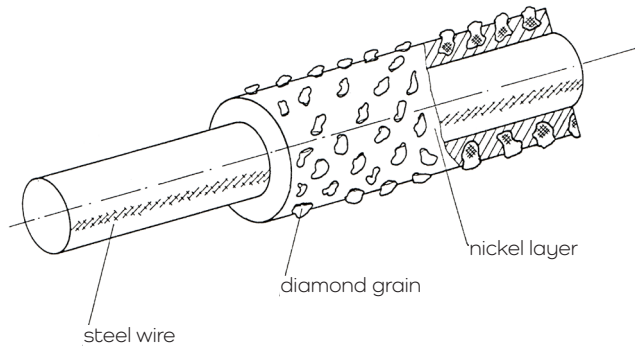


TECHNOLOGY

CONTACT

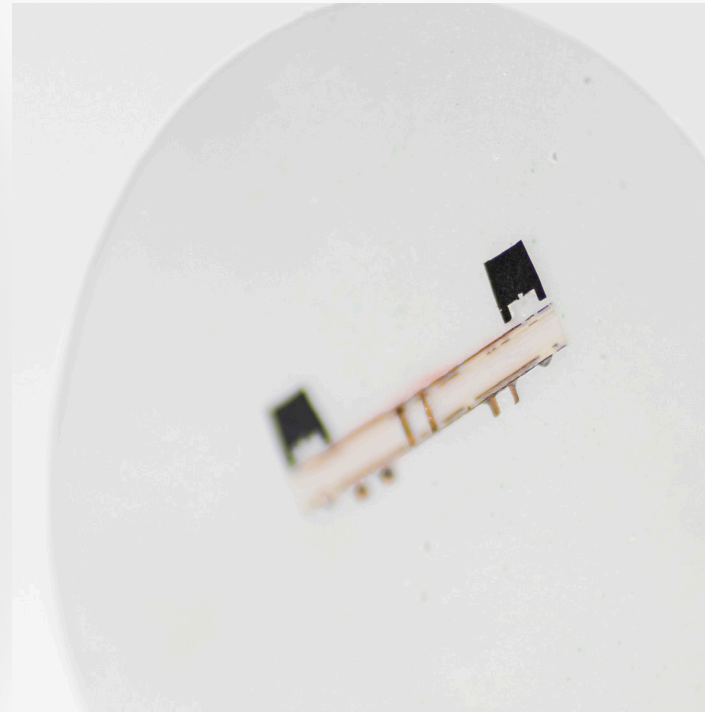
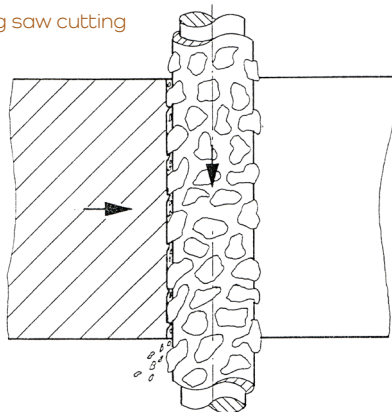
Structure of the diamond wire



Diamond wire sawing is a cutting process using wire with diamonds bonded to the surface by a nickel layer. The process is particularly suitable for cutting brittle-hard materials such as silicon, hard metal, sapphire or printed circuit boards. It is also ideal for cutting composite materials.

The surface finish of the surfaces sawn with diamond wire corresponds to that of a grinding process. This means that no further processing steps are necessary, saving time and resources, which is a major advantage of the process.

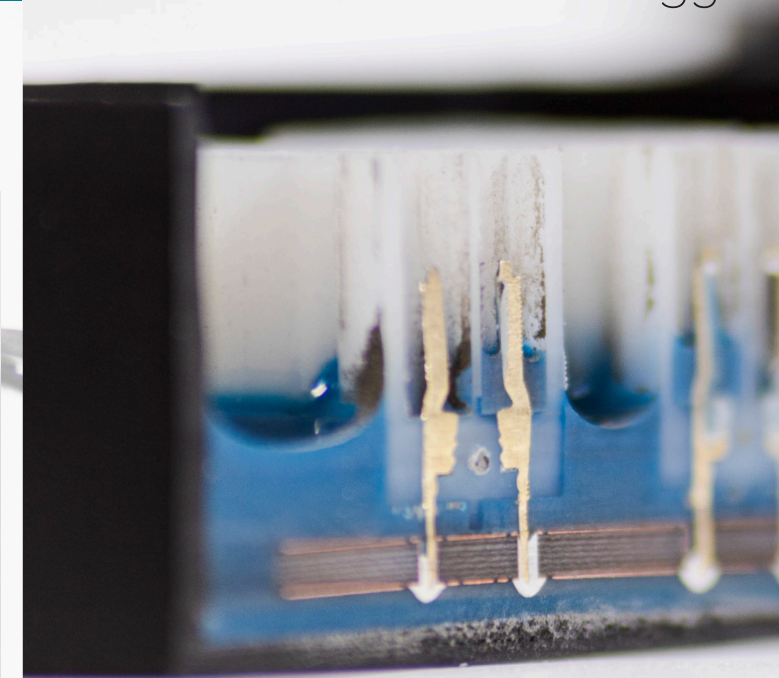
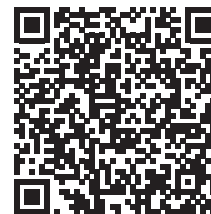
Diamond wire during saw cutting



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DIAMOND WIRE
Technology and Benefits

DIAMOND WIRE SAWS

BENEFITS

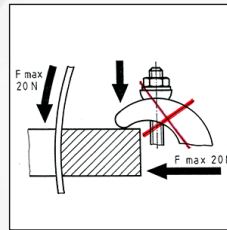
MATERIAL

DWLS - 3001

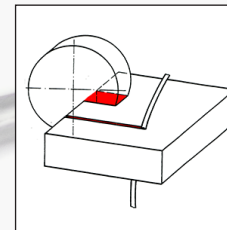
CNC-controlled
diamond wire saw
for contour cutting

Movement X 400mm
Movement Y 300mm
Cutting speed 12-30m/s
Core wire Ø120-300µm
Passage up to 300mm
Loop length 2700mm

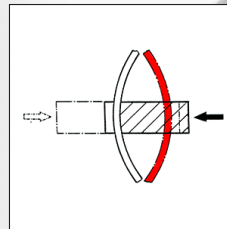
Intuitive control
with touch display



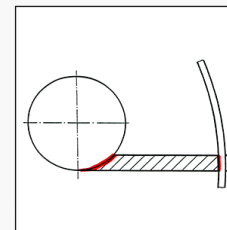
low infeed and
cutting forces



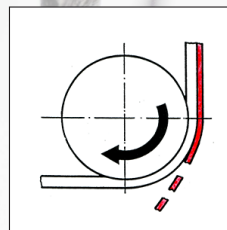
small cutting width
600-160µm



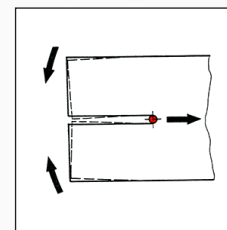
2D cuts through all-round
coated tool



short contact length and
low heat emission



self-cleaning and
flexible tool



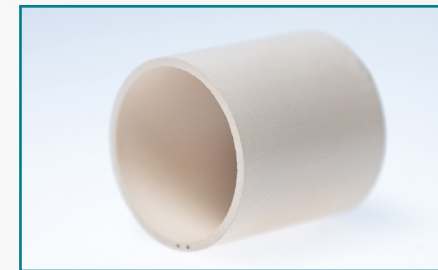
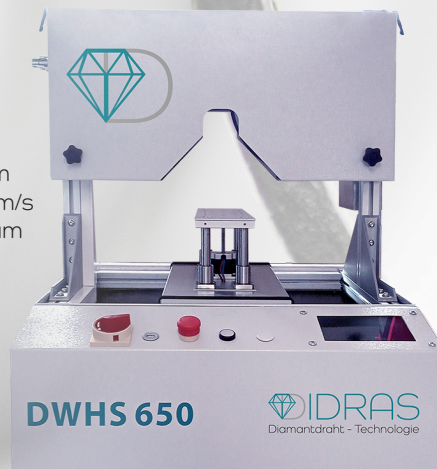
clamp-free tool -
only line contact

DWHS - 650

Laboratory table saw
for straight cutting

Vertical stroke 150mm
Cutting speed 10-50m/s
Core wire Ø120-300µm
Passage up to 75mm
Loop length 1690mm

Intuitive control
with touch display



Ceramics



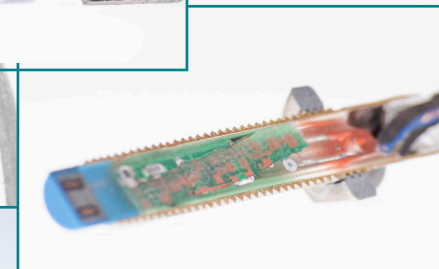
Carbide



Fibre
composites



Electronics



Sapphire



Combined
materials

